

Hyper SuperServer SYS-122HA-TN-LCC

1U Hyper with 12 hot-swap 2.5" NVMe bays and 2 PCIe 5.0 x16 + 1 PCIe 5.0 x16 AIOM slot



Key Applications

Virtualization, High Performance Computing, Artificial Intelligence, Data Analytics,

Key Features

- Dual Intel® Xeon® 6900-Series Processors with P-cores up to 500W with D2C liquid cooling;
- Up to 24 DIMMs supporting up to 6TB 6400MT/s DDR5 RDIMM or 3TB 8800MT/s DDR5 MRDIMM;
- 12 2.5" hot-swap NVMe drive bays;
- 2 PCIe 5.0 x16 slots (full-height, 10.5" length);
- 1 AIOM/OCP 3.0 NIC slot for flexible networking options;
- Redundant titanium level power supplies with options from 1600W to 2600W;
- 1U Rackmount chassis with 30.66" (778.7mm) depth;



Form Factor	1U Rackmount Enclosure: 437 x 43 x 778.7mm (17.2" x 1.7" x 30.66") Package: 672 x 224 x 1100mm (26.46" x 8.82" x 43.31")
Processor	Dual Socket BR (LGA-7529) Intel® Xeon® 6900 series processors with P-cores Up to 128C/256T; Up to 504MB Cache per CPU
System Memory	Slot Count: 24 DIMM slots Max Memory (1DPC): Up to 6TB 6400MT/s ECC DDR5 RDIMM Max Memory (1DPC): Up to 3TB 8800MT/s ECC DDR5 MRDIMM
Drive Bays Configuration	Default: Total 12 bays <ul style="list-style-type: none">• 12 front hot-swap 2.5" NVMe drive bays M.2: 2 M.2 PCIe 5.0 x2 NVMe slots (M-key 2280/22110)
Expansion Slots	Default <ul style="list-style-type: none">• 2 PCIe 5.0 x16 FH/10.5" L slots• 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports(rear) 1 USB 3.0 port(front) Video: 1 VGA port

(Front View – System)



Drive Bay	Description
6	Hot-swap 2.5" NVMe/SAS3/SATA3 Drive Bays (NVMe from CPU1)
6	Hot-swap 2.5" NVMe/SAS3/SATA3 Drive Bays (NVMe from CPU2)

*NVMe, SAS3, or SATA3 support requires additional parts from the optional parts list.

(Rear View – System)



Slot Description
PCIe 5.0 x16 FH/10.5L
PCIe 5.0 x16 FH/10.5L
PCIe 5.0 x16 AIO/M (OCP 3.0)
Liquid Cooling Tubes

CPU1 CPU2 Liquid Cooling

System Cooling

Fans: Up to 8 counter-rotating 40x40x56mm Fan(s)
 Liquid Cooling: Direct to Chip (D2C) Cold Plate

Power Supply

2x 1600W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies

System BIOS

BIOS Type: AMI 64MB SPI Flash

Management

SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!

PC Health Monitoring

CPU: Monitors for CPU Cores, Chipset Voltages, Memory
 FAN: Fans with tachometer monitoring
 Status monitor for speed control
 Pulse Width Modulated (PWM) fan connectors
 Temperature: Monitoring for CPU and chassis environment
 Thermal Control for fan connectors

Dimensions and Weight

Weight: Gross Weight: 41.4 lbs (18.8 kg)
 Net Weight: 19.2 lbs (8.7 kg)
 Available Color: Silver

Operating Environment

Name: A2
 Operating Temperature: 10°C to 35°C (50°F to 95°F)
 Non-operating Temperature: -30°C to 60°C (-40°F to 140°F)
 Operating Relative Humidity: 8% to 80% (max 21° DP; non-condensing)
 Non-operating Relative Humidity: 8% to 90% (max 38° DP; non-condensing)

Motherboard

[Super X14DBM-APL](#)

Chassis

CSE-HS101-R000NFP